



BAT754 series

Schottky barrier diodes

Rev. 3 — 9 October 2012

Product data sheet

1. Product profile

1.1 General description

Planar Schottky barrier diodes with an integrated guard ring for stress protection, encapsulated in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

1.2 Features and benefits

- Low forward voltage
- Low capacitance
- AEC-Q101 qualified

1.3 Applications

- Ultra high-speed switching
- Line termination
- Voltage clamping
- Reverse polarity protection

1.4 Quick reference data

Table 1. Quick reference data

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per diode						
V_R	reverse voltage		-	-	30	V
V_F	forward voltage	$I_F = 100\text{ mA}$	[1]	-	600	mV
I_R	reverse current	$V_R = 25\text{ V}$	[1]	-	2	μA

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

2. Pinning information

Table 2. Pinning

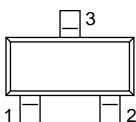
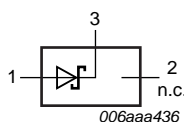
Pin	Description	Simplified outline	Graphic symbol
BAT754			
1	anode		
2	not connected		
3	cathode		



Table 2. Pinning ...continued

Pin	Description	Simplified outline	Graphic symbol
BAT754A			
1	cathode (diode 1)		 006aaa439
2	cathode (diode 2)		
3	common anode		
BAT754C			
1	anode (diode 1)		 006aac984
2	anode (diode 2)		
3	common cathode		
BAT754S			
1	anode (diode 1)		 006aaa437
2	cathode (diode 2)		
3	cathode (diode 1), anode (diode 2)		

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BAT754 series	-	plastic surface-mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
BAT754	2K*
BAT754A	2L*
BAT754C	2M*
BAT754S	2N*

[1] * = placeholder for manufacturing site code.

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per diode					
V_R	reverse voltage		-	30	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$		300	mA
I_{FSM}	non-repetitive peak forward current	sine wave; $t_p < 8.3$ ms	[1] -	600	mA
Per device; one diode loaded					
T_j	junction temperature		-	125	°C
T_{amb}	ambient temperature		-55	+125	°C
T_{stg}	storage temperature		-65	+150	°C

[1] $T_j = 25$ °C before surge.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device; one diode loaded						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] -	-	500	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

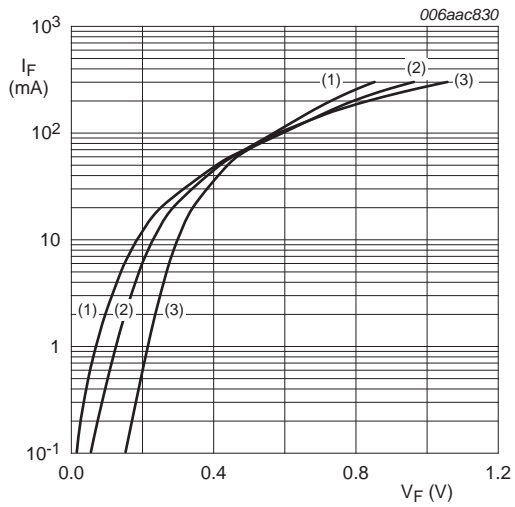
7. Characteristics

Table 7. Characteristics

$T_{amb} = 25$ °C unless otherwise specified.

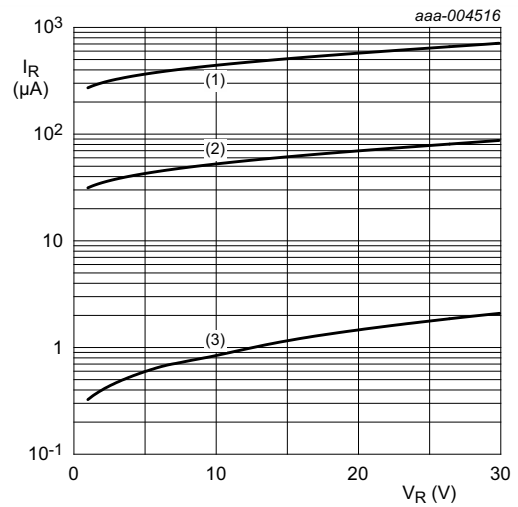
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage		[1]			
		$I_F = 0.1$ mA	-	-	200	mV
		$I_F = 1$ mA	-	-	260	mV
		$I_F = 10$ mA	-	-	340	mV
		$I_F = 30$ mA	-	-	420	mV
		$I_F = 100$ mA	-	600	-	mV
I_R	reverse current	$V_R = 25$ V	[1] -	-	2	μA
C_d	diode capacitance	$f = 1$ MHz; $V_R = 1$ V	-	-	10	pF

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.



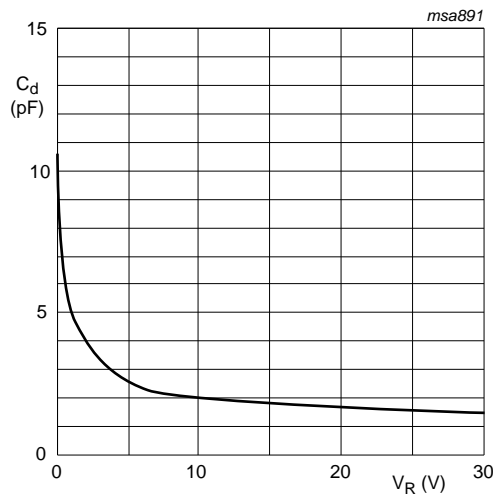
- (1) $T_{amb} = 125\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 125\text{ °C}$
- (2) $T_{amb} = 85\text{ °C}$
- (3) $T_{amb} = 25\text{ °C}$

Fig 2. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}; T_{amb} = 25\text{ °C}$

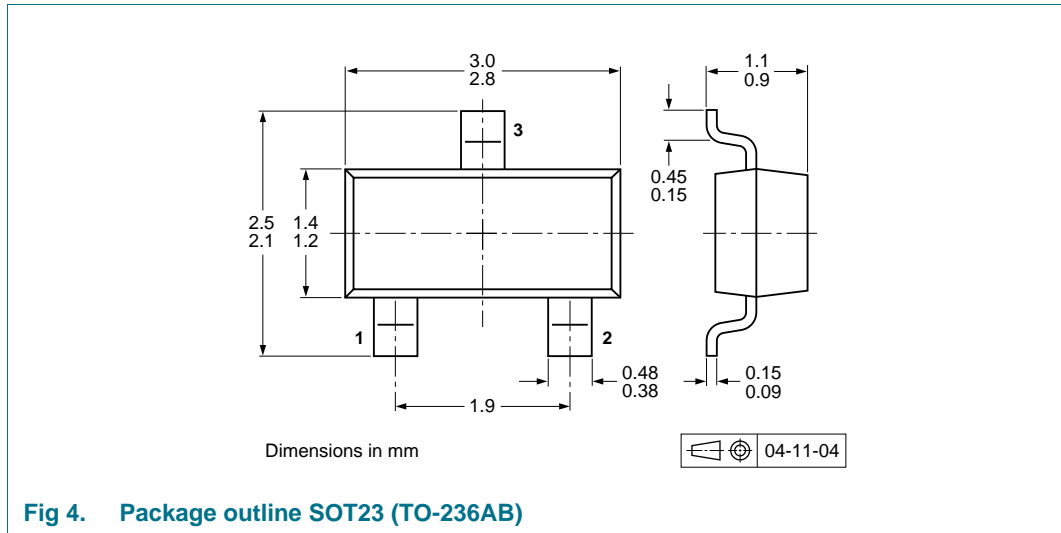
Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
BAT754 series	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

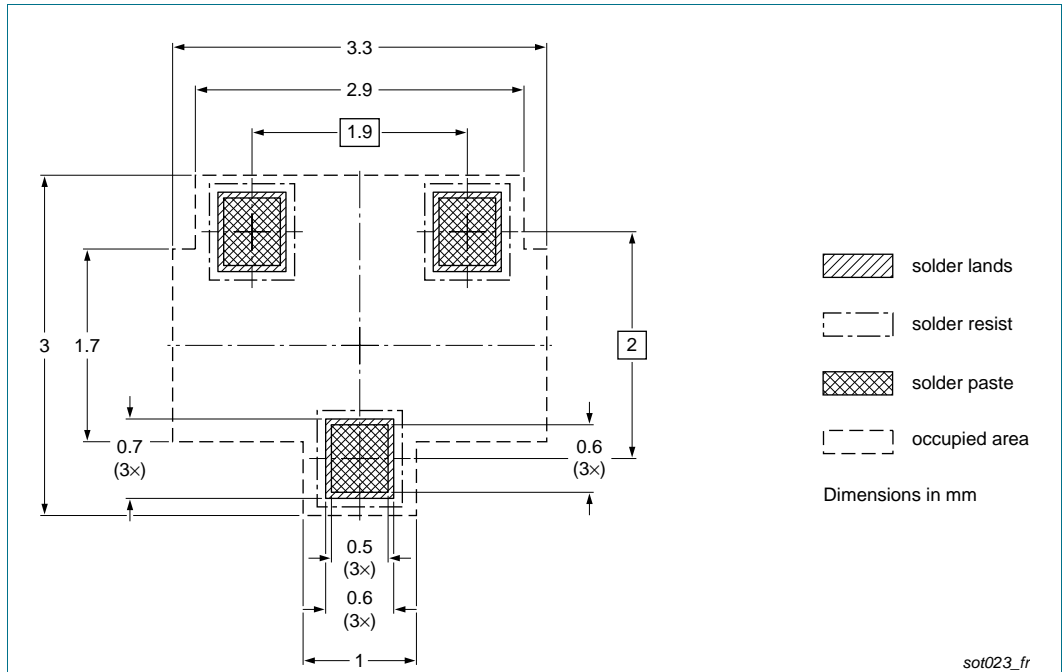


Fig 5. Reflow soldering footprint SOT23 (TO-236AB)

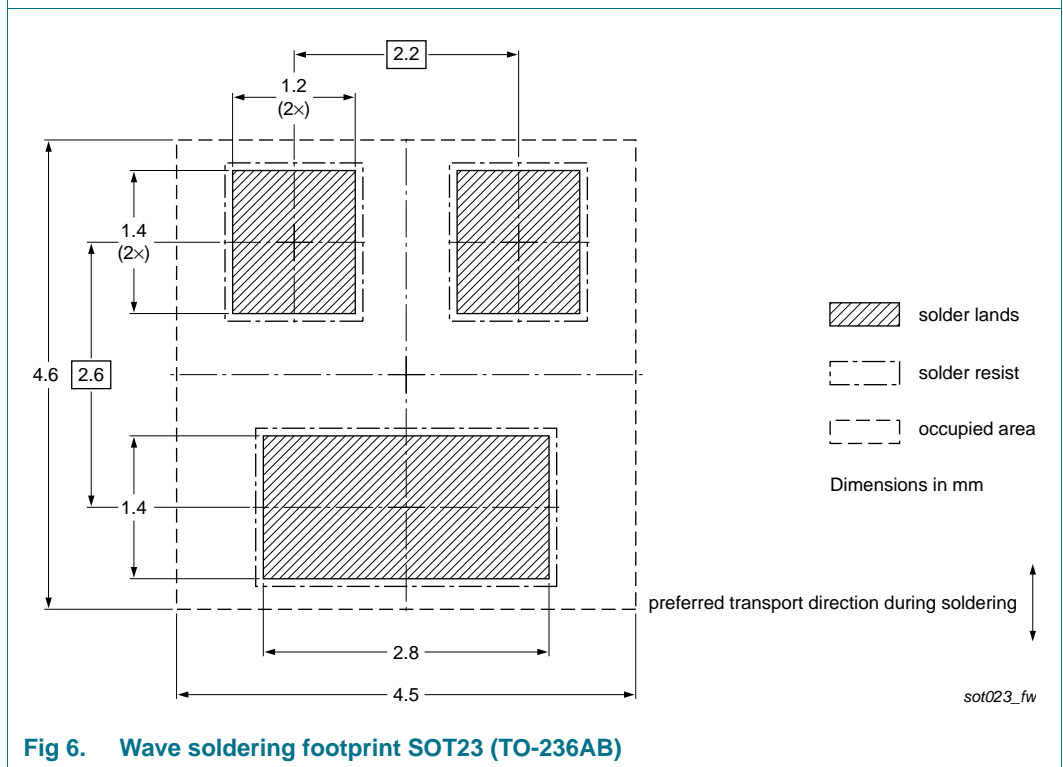


Fig 6. Wave soldering footprint SOT23 (TO-236AB)

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAT754_SER v.3	20121009	Product data sheet	-	BAT754_SERIES v.2
Modifications:	<ul style="list-style-type: none"> • The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 1: updated • Section 4: updated • Table 5: I_{FSM} conditions updated; changed T_{amb} minimum value to comply with AEC-Q101 • Figure 1 and 2: updated • Section 8 "Test information": added • Figure 4: replaced by minimized package outline drawing • Section 10 "Packing information": added • Section 11 "Soldering": added • Section 13 "Legal information": updated 			
BAT754_SERIES v.2	20030325	Product data sheet	-	BAT754_SERIES v.1
BAT754_SERIES v.1	19990805	Product specification	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 9 October 2012
Document identifier: BAT754_SER